# High-Efficiency, 1A, 5.5V Input Synchronous Step-Down Regulator

### **General Description**

The SY20019 high-efficiency 1.5MHz synchronous step-down DC/DC regulator operates over a wide input voltage range of 2.5V to 5.5V, and can deliver an output current up to 1A. It integrates a main switch and a synchronous switch with very low  $R_{\text{DS}(\text{ON})}$  to minimize conduction loss. The 1.5MHz pseudoconstant switching frequency allows for small external inductor and capacitor values.

The SY20019 uses constant-off-time and peakcurrent-mode control to achieve fast transient responses. It provides overcurrent and short-circuit protection.

The SY20019 is available in a space-saving, low-profile SOT563 package.

#### **Features**

- 2.5V to 5.5V Input Voltage Range
- Up to 1A Output Current
- 55µA Low Quiescent Current
- Low R<sub>DS(ON)</sub> for Internal Switches: 170mΩ
   Top, 100mΩ Bottom
- 1.5MHz Switching Frequency Minimizes Required External Components
- Internal Soft-Start Limits Inrush Current
- 100% Dropout Operation
- Power-Good Indicator
- Hiccup Mode for Short-Circuit Protection
- Output Auto-Discharge Function
- RoHS-Compliant and Halogen-Free
- Compact Package: SOT563

### **Applications**

- Set-Top Boxes
- USB Dongles
- Media Players
- Smartphones

# **Typical Application**

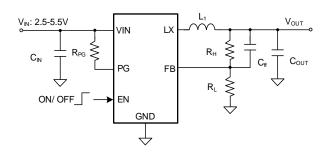


Figure 1. Schematic Diagram

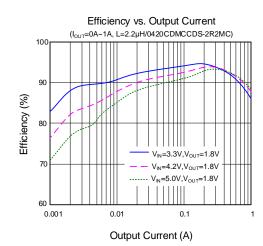


Figure 2. Efficiency vs. Output Current



# **Ordering Information**

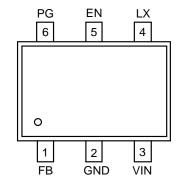
Ordering Part Number	Details
SY20019ARC	PFM Operation Pin 6 Power-Good (PG)
SY20019BARC	PFM Operation Pin 6 NC (No PG)
SY20019EARC	Forced PWM Operation Pin 6 Power-Good (PG)
SY20019FARC	Forced PWM Operation Pin 6 NC (No PG)

# Package Information

Part Number	Top Mark	Package type
SY20019ARC	L9 <i>xyz</i>	
SY20019BARC	M2xyz	SOT563
SY20019EARC	E2xyz	RoHS-Compliant and Halogen-Free
SY20019FARC	M3xyz	

x = year code, y = week code, z = lot number code

# Pinout (top view)\*



\*Pin 6 is NC for SY20019BARC and SY20019FARC

# **Pin Description**

Pin No	Pin Name	Pin Description
1	FB	Output feedback pin. Connect this pin to the center point of the output resistor-divider (as shown in Figure 1) to program the output voltage: $V_{OUT} = 0.6 \times (1+R_H/R_L)$ .
2	GND	Ground pin.
3	$V_{IN}$	Input pin. Decouple this pin to the GND pin with at least a 10µF ceramic capacitor.
4	LX	Inductor pin. Connect this pin to the switching node of the inductor.
5	EN	Enable pin. Pull low to disable the device, pull high to enable. Do not leave this pin floating.
6	PG	SY20019ARC/SY20019EARC: Power-good indicator pin. This pin is high-impedance if the output is between 90% and 120% of the regulation voltage; otherwise, it is driven low. Connect a pullup resistor to the input.
	NC	SY20019BARC/SY20019FARC: NC, leave it floating or connected to GND.

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# **Block Diagram**

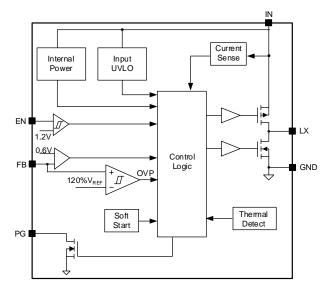


Figure 3. Block Diagram

**Absolute Maximum Ratings** 

Parameter (Note 1)	N	/lin	Max	Unit
IN	-(	0.3	6	
EN, FB, PG	-(	0.3	IN+ 0.6	٧/
LX	-(	0.3	6	\ \
LX, 20ns duration		-3	7	
Junction Temperature, Operating		40	150	
Lead Temperature (Soldering,10sec.)			260	°C
Storage Temperature		65	150	

### **Thermal Information**

Parameter (Note 2)	Тур	Unit
θ <sub>JA</sub> Junction-to-Ambient Thermal Resistance	105	°C/W
θ <sub>JC</sub> Junction-to-Case Thermal Resistance	30	C/VV
$P_D$ Power Dissipation $T_A = 25$ °C	0.95	W

**Recommended Operating Conditions** 

Parameter (Note 3)	Min	Max	Unit
IN	2.5	5.5	\/
Output Voltage	0.6	5.5	V
Output Current		1	Α
Junction Temperature	-40	125	°C

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### **Electrical Characteristics**

 $(V_{IN} = 5V, V_{OUT} = 1.8V, L = 2.2\mu H, C_{OUT} = 10\mu F, T_{J} = 25^{\circ}C, unless otherwise specified)$ 

Parameter		Symbol	Test Conditions	Min	Тур	Max	Unit
	Voltage	V <sub>IN</sub>		2.5		5.5	V
	UVLO, Rising	V <sub>IN,UVLO</sub>			2.45	2.5	V
	UVLO, Hysteresis	V <sub>IN,HYS</sub>			150		mV
Input	Quiescent Current	lα	V <sub>FB</sub> = 105% × VREF (For SY20019ARC and SY20019BARC Only)		55		μΑ
	Shutdown Current	I <sub>SHDN</sub>	$V_{EN} = 0V$		0.1	1	μΑ
FB	Reference Voltage	VREF	Iout = 0.5A, CCM	0.59 1	0.6	0.609	V
	Input Current	I <sub>FB</sub>	$V_{EN} = 2V$ , $V_{FB} = 1V$	-50	0	50	nA
Power Switch	On-Resistance	R <sub>DS</sub> (ON)HS			170		mΩ
1 Ower Switch	Current Limit	I <sub>LMT,HS</sub>		1.5		2.5	Α
Synchronous Rectifier	On-Resistance	R <sub>DS(ON)LS</sub>			100		mΩ
Discharge FET Resistance		R <sub>DIS</sub>			50		Ω
	Input Voltage High	$V_{EN,H}$		1.2			V
Enable(EN)	Input Voltage Low	V <sub>EN,L</sub>				0.4	V
	Input Current	I <sub>EN</sub>	$V_{EN} = 2V$			1 0.609 50 2.5	μΑ
Soft-Start (SS)	Turn-On Delay Time	ton,dly	From EN high to LX start switching		0.25		ms
	Soft-Start Time	tss	Vout from 0% to 100%		5.5 2.45 2.5 150 55 0.1 1 0.6 0.609 0 50 170 2.5 100 50 0.4 2	ms	
Undervoltage Protection	Threshold	Vuvp			50		%V <sub>RE</sub> F
	Delay	t <sub>UVP,DLY</sub>			10		μs
UVP/OCP Hiccup On-Time		thiccup,on			1.45		ms
UVP/OCP Hiccup Off-Time		thiccup,off			1.45		ms
			V <sub>FB</sub> falling, fault				%
	Thresholds	V <sub>PG</sub>	V <sub>FB</sub> rising, good				%
Power-Good	Tillesiloids	VPG	V <sub>FB</sub> rising, fault				%
1 Ower-Good			V <sub>FB</sub> falling, good				%
	Delay	t <sub>PG,R</sub>	V <sub>FB</sub> rising, good				μs
	Delay	t <sub>PG,F</sub>	V <sub>FB</sub> falling, fault				μs
Switching Frequency		fsw	Iоит = 0.5A, ССМ				MHz
Min On-Time		ton,min			50		ns
Maximum Duty Cycle		D <sub>MAX</sub>		100			%
Thermal Shutdown Temperature		T <sub>SD</sub>					°C
Thermal Shutdown Hysteres	sis	T <sub>HYS</sub>			20		°C

**Note 1**: Stresses beyond the "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**Note 2:**  $\theta_{JA}$  of SY20019 is measured in the natural convection at  $T_A = 25^{\circ}C$  on a 2oz two-layer Silergy evaluation board. Pin 4 is the case position for SY20019  $\theta_{JC}$  measurement.

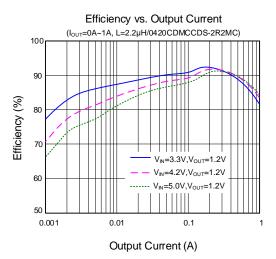
**Note 3:** The device is not guaranteed to function outside its operating conditions.

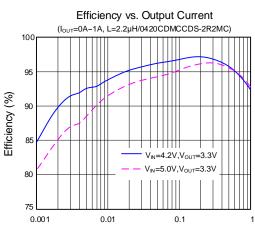


# **Typical Performance Characteristics**

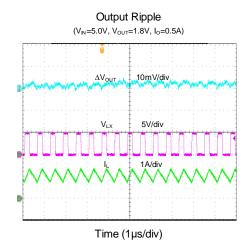
 $(T_A = 25^{\circ}C, V_{IN} = 5V, V_{OUT} = 1.8V, L = 2.2\mu H, C_{OUT} = 10\mu F, unless otherwise noted)$ 

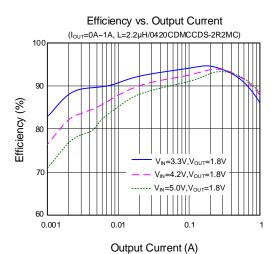
#### **SY20019ARC**

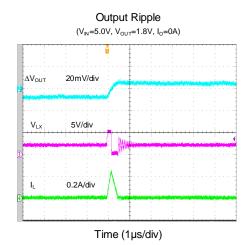


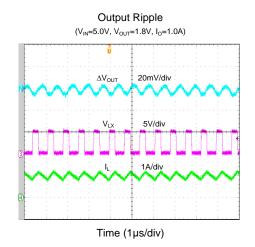


Output Current (A)



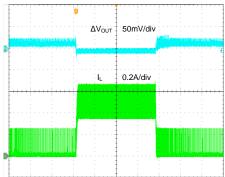






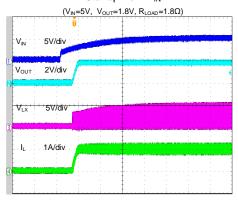






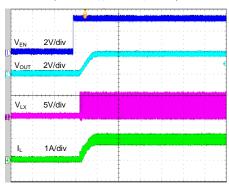
Time (800µs/div)

#### Startup from V<sub>IN</sub>



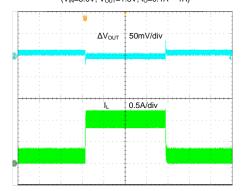
Time (2ms/div)

# Startup from Enable $(V_{IN}=5.0V, V_{OUT}=1.8V, R_{LOAD}=1.8\Omega)$



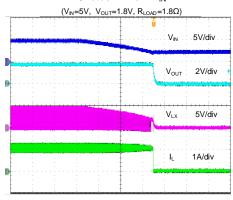
Time (800µs/div)

# Load Transient (V<sub>IN</sub>=5.0V, V<sub>OUT</sub>=1.8V, I<sub>O</sub>=0.1A ~ 1A)



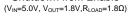
Time (800µs/div)

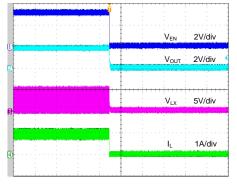
#### Shutdown from V<sub>IN</sub>



Time (2ms/div)

#### Shutdown from Enable

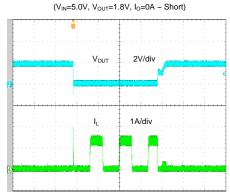




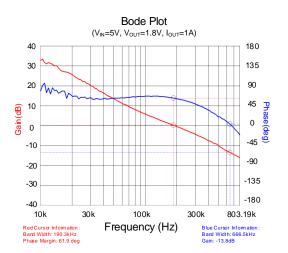
Time (800µs/div)



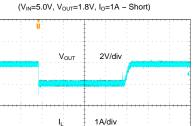
### Short Circuit Protection



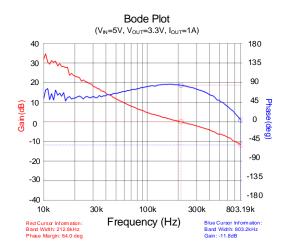
Time (2ms/div)



### Short Circuit Protection



Time (2ms/div)





### Operation

The SY20019 high-efficiency 1.5MHz synchronous step-down DC/DC regulator operates over an input voltage range of 2.5V to 5.5V, and can deliver an output current up to 1A. It integrates a main switch and a synchronous switch with very low R<sub>DS(ON)</sub> to minimize conduction loss. The 1.5MHz pseudoconstant switching frequency allows for small external inductor and capacitor values.

The SY20019 uses constant-off-time and peak-current-mode control to achieve fast transient responses. When the top FET's current-sense signal reaches internal V<sub>COMP</sub>, the top FET will turn off and the bottom FET will turn on for a fixed period of time (constant t<sub>OFF</sub>). tope is internally calculated according to the input voltage, output voltage, and desired switching frequency (fsw):

$$t_{OFF} = \frac{1 - V_{OUT}/V_{IN}}{f_{SW}}$$

The bottom FET turns off after a period of toff.

The SY20019 is available in a space-saving, low-profile SOT563 package.

### **Applications Information**

The selection process for the input capacitor  $C_{\text{IN}}$ , output capacitor  $C_{\text{OUT}}$ , output inductor L, and feedback resistors (R<sub>H</sub> and R<sub>L</sub>) is described in the following sections.

#### Feedback Resistor-Divider RH and RL

Choose  $R_H$  and  $R_L$  to program the proper output voltage. A value between  $1k\Omega$  and  $1M\Omega$  is recommended for both resistors. If  $R_L=120k\Omega$  is chosen, then  $R_H$  can be calculated as follows:

$$R_H = \frac{(V_{OUT} - 0.6V) \times R_L}{0.6V}$$

#### Input Capacitor CIN

For the best performance, select a typical X5R or better grade ceramic capacitor with a 6.3V rating, and at least  $10\mu F$  capacitance. The capacitor should be placed as close as possible to the device, while also minimizing the loop area formed by  $C_{IN}$  and the IN/GND pins.

When selecting an input capacitor, ensure that its voltage rating is at least 20% greater than the maximum voltage of the input supply. X5R or X7R dielectric types are the most often selected due to their small size, low cost, surge current capability, and high RMS current rating over a wide temperature and voltage range.

In situations where the input rail is supplied through long wires, it is recommended to add some bulk capacitance like electrolytic-, tantalum-, or polymer-type capacitors to reduce the overshoot and ringing caused by the added parasitic inductance.

Consider the RMS current rating of the input capacitor, paralleling additional capacitors if required to meet the calculated RMS ripple current.

$$I_{CIN\_RMS} = I_{OUT} \times \sqrt{D \times (1 - D)}$$

The worst-case condition occurs at D = 0.5, then

$$I_{CIN\_RMS,MAX} = \frac{I_{OUT}}{2}$$

For simplicity, use an input capacitor with an RMS current rating greater than 50% of the maximum load current.

The input capacitor value determines the input voltage ripple of the converter. If there is a voltage ripple requirement in the system, choose an appropriate input capacitor that meets the specification.

Given the very low ESR and ESL of ceramic capacitors, the input voltage ripple can be estimated using the formula:

$$V_{CIN\_RIPPLE,CAP} = \frac{I_{OUT}}{f_{SW} \times C_{IN}} \times D \times (1 - D)$$

The worst-case condition occurs at D = 0.5, then

$$V_{CIN\_RIPPLE,CAP,MAX} = \frac{I_{OUT}}{4 \times f_{SW} \times C_{IN}}$$

The capacitance value is less important than the RMS current rating. A single  $10\mu F$  X5R capacitor is sufficient in most applications.

#### **Output Capacitor Cout**

Select the output capacitor  $C_{OUT}$  to handle the output ripple requirements. Both steady-state ripple and transient requirements must be taken into consideration when selecting  $C_{OUT}$ . For the best performance, use an X5R or better grade ceramic capacitor with a 6.3V rating, and capacitance of at least  $10\mu F$ .

For applications where the design must meet stringent ripple requirements, the following considerations must be followed.

The output voltage ripple at the switching frequency is caused by the inductor-current ripple ( $\Delta I_L$ ) on the output capacitor's ESR (ESR ripple), as well as the stored charge (capacitive ripple). When calculating total ripple, consider both.





$$V_{RIPPLE,ESR} = \Delta I_L \times ESR$$
 
$$V_{RIPPLE,CAP} = \frac{\Delta I_L}{8 \times C_{OUT} \times f_{SW}}$$

The capacitive ripple might be higher because the effective capacitance for ceramic capacitors decreases with the voltage across the terminals. The voltage derating is usually included as a chart in the capacitor datasheet, and the ripple can be recalculated after taking the target output voltage into account.

#### **Output Inductor L**

Consider the following when choosing this inductor:

1) Choose the inductance to provide a ripple current that is approximately 40% of the maximum output current. The recommended inductance is calculated as:

$$L = \frac{V_{OUT}(1 - V_{OUT} / V_{IN,MAX})}{f_{sw} \times I_{OUT,MAX} \times 0.4}$$

where fsw is the switching frequency and IOUT, MAX is the maximum load current.

The SY20019 has high tolerance for ripple current amplitude variation. As a result, the final choice of inductance can vary slightly from the calculated value with no significant performance impact.

The inductor's saturation current rating must be greater than the peak inductor current under full load:

$$I_{SAT,MIN} > I_{OUT,MAX} + \frac{V_{OUT}(1 - V_{OUT}/V_{IN,MAX})}{2 \times f_{SW} \times L}$$

3) The DCR of the inductor and the core loss at the switching frequency must be low enough to achieve the desired efficiency requirement. Use an inductor with DCR less than  $50 \text{m}\Omega$  to achieve good overall efficiency.

#### Overcurrent and Short-Circuit Protection

With load current increasing, as soon as the high-side FET current exceeds the peak current-limit threshold, the high-side FET will turn off. If the load current continues to increase, the output voltage will drop. When the output voltage falls below 50% of the regulation level, the output undervoltage protection will be activated and the SY20019 will operate in hiccup mode. The hiccup frequency is 350Hz and the hiccup duty cycle is 50%. If the hard short is removed, the SY20019 will return to normal operation.

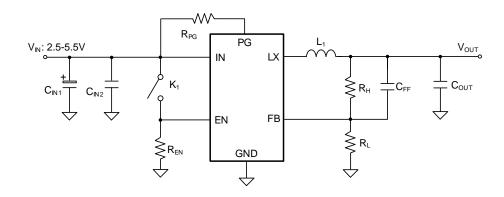
#### **Load-Transient Considerations**

The SY20019 regulator integrates the compensation components to achieve good stability and fast transient responses. In some applications, adding a 22pF ceramic capacitor in parallel with RH may further speed up the load-transient responses, and is therefore recommended applications large load-transient with requirements.

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# **Application Schematic** (Vout = 1.8V)



### **BOM List**

Reference Designator	Description	Part Number	Manufacturer
L <sub>1</sub>	2.2µH	0420CDMCCDS-2R2MC	Sumida
C <sub>IN1</sub>	100µF/25V(electrolytic capacitor)		
C <sub>IN2</sub>	10μF/6.3V, 0603, X5R	C1608X5R0J106M	TDK
C <sub>FF</sub>	22pF/50V, 0603, X5R	C1608C0G1H220J	TDK
Соит	10μF/6.3V, 0603, X5R	C1608X5R0J106M	TDK
R <sub>EN</sub>	1MΩ, 0603		
R <sub>PG</sub>	100kΩ, 0603		
R <sub>H</sub>	100kΩ, 0603, 1%		
R∟	49.9kΩ, 0603, 1%		

# **Recommended Component Values for Typical Applications**

V <sub>OUT</sub> (V)	R <sub>H</sub> (kΩ)	$R_L(k\Omega)$	C <sub>FF</sub> (pF)	L/(Rated/Saturating Current)	C <sub>out</sub>
1.2	49.9	49.9	22	2.2µH/(4.3A/6.3A)	10μF/6.3V, 0603, X5R
1.8	100	49.9	22	2.2µH/(4.3A/6.3A)	10μF/6.3V, 0603, X5R
3.3	100	22.1	22	2.2µH/(4.3A/6.3A)	10μF/6.3V, 0603, X5R



### **Layout Design**

For optimal design, follow these PCB layout considerations:

- For minimum noise and maximum efficiency, place the following components close to the IC: C<sub>IN</sub>, L1, R<sub>H</sub>, and R<sub>L</sub>.
- To achieve the best thermal and noise performance, maximize the PCB copper area connecting to the GND pin. A ground plane is highly recommended if board space allows.
- C<sub>IN</sub> must be close to pins IN and GND. Minimize the loop area formed by C<sub>IN</sub>, V<sub>IN</sub>, and GND.
- To reduce the switching noise, minimize the PCB copper area connected to the LX pin.
- R1, R2, and the trace connected to the FB pin must not be adjacent to the LX net on the PCB layout, in order to reduce crosstalk.

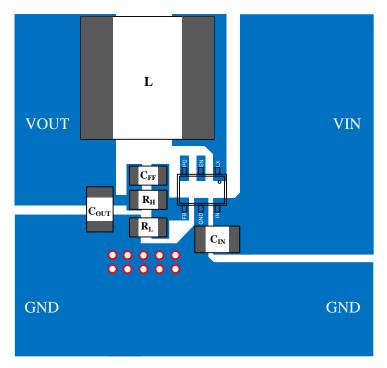
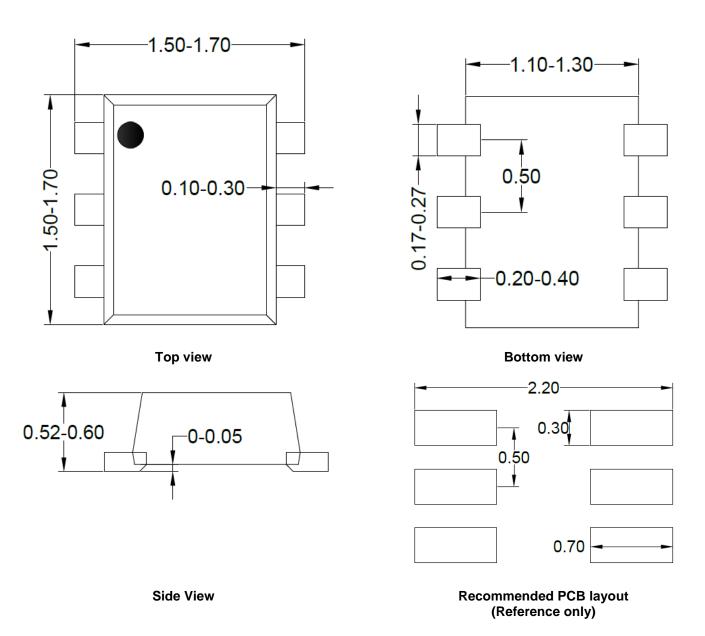


Figure 3. Suggested PCB Layout



# **SOT563 Package Outline**

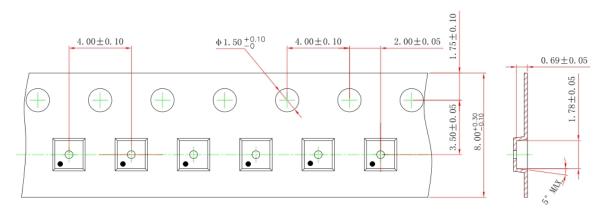


Note: All dimensions are in millimeters and exclude mold flash and metal burr.



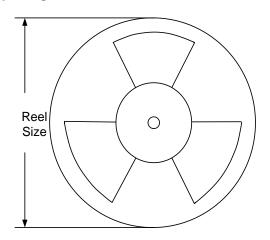
# **Taping & Reel Specification**

### SOT563 taping orientation



Feeding Direction ----

### Carrier tape and reel specification for packages



Package type	Tape width (mm)	Pocket pitch(mm)	Reel size (Inch)	Trailer length(mm)	Leader length (mm)	Qty per reel
SOT563	8	4	7"	280	160	5000

Others: NA



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